

#### Is Now Part of



## ON Semiconductor®

## To learn more about ON Semiconductor, please visit our website at www.onsemi.com

Please note: As part of the Fairchild Semiconductor integration, some of the Fairchild orderable part numbers will need to change in order to meet ON Semiconductor's system requirements. Since the ON Semiconductor product management systems do not have the ability to manage part nomenclature that utilizes an underscore (\_), the underscore (\_) in the Fairchild part numbers will be changed to a dash (-). This document may contain device numbers with an underscore (\_). Please check the ON Semiconductor website to verify the updated device numbers. The most current and up-to-date ordering information can be found at <a href="www.onsemi.com">www.onsemi.com</a>. Please email any questions regarding the system integration to Fairchild <a href="guestions@onsemi.com">guestions@onsemi.com</a>.

ON Semiconductor and the ON Semiconductor logo are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any EDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officer



September 2000 Revised May 2005

#### 74LCX162244

# Low Voltage 16-Bit Buffer/Line Driver with 26 $\Omega$ Series Resistors in Outputs

#### **General Description**

The LCX162244 contains sixteen non-inverting buffers with 3-STATE outputs designed to be employed as a memory and address driver, clock driver, or bus oriented transmitter/receiver. The device is nibble controlled. Each nibble has separate 3-STATE control inputs which can be shorted together for full 16-bit operation.

The LCX162244 is designed for low voltage (2.5V or 3.3V)  $\rm V_{CC}$  applications with capability of interfacing to a 5V signal environment.

In addition, the outputs include equivalent 26 $\Omega$  (nominal) series resistors to reduce overshoot and undershoot and are designed to sink/source up to 12 mA at  $V_{CC}=3.0V$ .

The LCX162244 is fabricated with an advanced CMOS technology to achieve high speed operation while maintaining CMOS low power dissipation.

#### **Features**

- 5V tolerant inputs and outputs
- 2.3V-3.6V V<sub>CC</sub> specifications provided
- $\blacksquare$  Outputs include equivalent series resistance of  $26\Omega$  to make external termination resistors unnecessary and reduce overshoot and undershoot
- 5.3 ns  $t_{PD}$  max ( $V_{CC}$  = 3.0V), 20  $\mu$ A  $I_{CC}$  max
- Power down high impedance inputs and outputs
- $\pm 12$  mA output drive ( $V_{CC} = 3.0V$ )
- Implements patented noise/EMI reduction circuitry
- Latch-up performance exceeds 500 mA
- ESD performance:

Human body model > 2000V

Machine model > 200V

Also packaged in plastic Fine-Pitch Ball Grid Array (FBGA) (Preliminary)

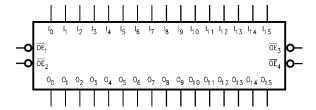
#### **Ordering Code:**

Order Number	Package Number	Package Description
74LCX162244GX (Note 1)	BGA54A (Preliminary)	54-Ball Fine-Pitch Ball Grid Array (FBGA), JEDEC MO-205, 5.5mm Wide [TAPE and REEL]
74LCX162244MEA (Note 2)	MS48A	48-Lead Small Shrink Outline Package (SSOP), JEDEC MO-118, 0.300" Wide
74LCX162244MTD (Note 2)	MTD48	48-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 6.1mm Wide

Note 1: BGA package available in Tape and Reel only

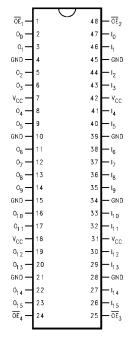
Note 2: Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.

#### **Logic Symbol**

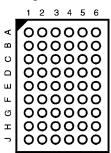


## **Connection Diagrams**

Pin Assignment for SSOP and TSSOP



Pin Assignment for FBGA



(Top Thru View)

### **Pin Descriptions**

Pin Names	Description
<del>OE</del> <sub>n</sub>	Output Enable Input (Active LOW)
I <sub>0</sub> -I <sub>15</sub>	Inputs
O <sub>0</sub> -O <sub>15</sub>	Outputs
NC	No Connect

#### **FBGA Pin Assignments**

	1	2	3	4	5	6
Α	O <sub>0</sub>	NC	OE <sub>1</sub>	OE <sub>2</sub>	NC	I <sub>0</sub>
В	O <sub>2</sub>	O <sub>1</sub>	NC	NC	I <sub>1</sub>	l <sub>2</sub>
С	O <sub>4</sub>	O <sub>3</sub>	V <sub>CC</sub>	V <sub>CC</sub>	I <sub>3</sub>	14
D	O <sub>6</sub>	O <sub>5</sub>	GND	GND	I <sub>5</sub>	I <sub>6</sub>
E	O <sub>8</sub>	O <sub>7</sub>	GND	GND	I <sub>7</sub>	I <sub>8</sub>
F	O <sub>10</sub>	O <sub>9</sub>	GND	GND	l <sub>9</sub>	I <sub>10</sub>
G	O <sub>12</sub>	O <sub>11</sub>	V <sub>CC</sub>	V <sub>CC</sub>	I <sub>11</sub>	I <sub>12</sub>
Н	O <sub>14</sub>	O <sub>13</sub>	NC	NC	I <sub>13</sub>	I <sub>14</sub>
J	O <sub>15</sub>	NC	OE <sub>4</sub>	$\overline{OE}_3$	NC	I <sub>15</sub>

#### **Truth Tables**

Inputs		Outputs
OE <sub>1</sub>	I <sub>0</sub> –I <sub>3</sub>	O <sub>0</sub> -O <sub>3</sub>
L	L	L
L	Н	Н
Н	X	Z

Inp	Outputs	
OE <sub>2</sub>	I <sub>4</sub> –I <sub>7</sub>	04-07
L	L	L
L	Н	Н
Н	X	Z

Inp	Outputs	
OE₃	I <sub>8</sub> –I <sub>11</sub>	O <sub>8</sub> -O <sub>11</sub>
L	L	L
L	Н	Н
Н	X	Z

Inp	Outputs	
OE <sub>4</sub>	I <sub>12</sub> -I <sub>15</sub>	O <sub>12</sub> -O <sub>15</sub>
L	L	L
L	Н	Н
Н	Х	Z

H = HIGH Voltage Level L = LOW Voltage Level

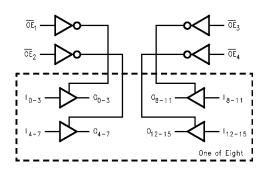
X = Immaterial Z = High Impedance

## **Functional Description**

The LCX162244 contains sixteen non-inverting buffers with 3-STATE standard outputs. The device is designed with  $26\Omega$  series resistors in the outputs. This design reduces line noise in applications such as memory address drivers, clock drivers and bus transceiver/transmitters. The device is nibble (4 bits) controlled with each nibble functioning identically, but independent of the other. The control pins

can be shorted together to obtain full 16-bit operation. The 3-STATE outputs are controlled by an Output Enable  $(\overline{OE}_n)$  input for each nibble. When  $\overline{OE}_n$  is LOW, the outputs are in 2-state mode. When  $\overline{OE}_n$  is HIGH, the outputs are in the high impedance mode, but this does not interfere with entering new data into the inputs.

#### **Logic Diagram**



## Absolute Maximum Ratings(Note 3)

Symbol	Parameter	Value	Conditions	Units
V <sub>CC</sub>	Supply Voltage	-0.5 to +7.0		V
VI	DC Input Voltage	-0.5 to +7.0		V
Vo	DC Output Voltage	-0.5 to +7.0	Output in 3-STATE	V
		$-0.5$ to $V_{CC} + 0.5$	Output in HIGH or LOW State (Note 4)	v
I <sub>IK</sub>	DC Input Diode Current	-50	V <sub>I</sub> < GND	mA
I <sub>OK</sub>	DC Output Diode Current	-50	V <sub>O</sub> < GND	mA
		+50	$V_O > V_{CC}$	IIIA
Io	DC Output Source/Sink Current	±50		mA
I <sub>CC</sub>	DC Supply Current per Supply Pin	±100		mA
I <sub>GND</sub>	DC Ground Current per Ground Pin	±100		mA
T <sub>STG</sub>	Storage Temperature	-65 to +150		°C

## **Recommended Operating Conditions** (Note 5)

Symbol	Parameter		Min	Max	Units
V <sub>CC</sub>	Supply Voltage	Operating	2.0	3.6	V
		Data Retention	1.5	3.6	V
VI	Input Voltage		0	5.5	V
Vo	Output Voltage	HIGH or LOW State	0	V <sub>CC</sub>	V
		3-STATE	0	5.5	v
I <sub>OH</sub> /I <sub>OL</sub>	Output Current	$V_{CC} = 3.0V - 3.6V$		±12	
		$V_{CC} = 2.7V - 3.0V$		±8	mA
		$V_{CC} = 2.3V - 2.7V$		±4	
T <sub>A</sub>	Free-Air Operating Temperature		-40	85	°C
Δt/ΔV	Input Edge Rate, V <sub>IN</sub> = 0.8V–2.0V, V <sub>CC</sub> = 3.0V		0	10	ns/V

Note 3: The Absolute Maximum Ratings are those values beyond which the safety of the device cannot be guaranteed. The device should not be operated at these limits. The parametric values defined in the Electrical Characteristics tables are not guaranteed at the Absolute Maximum Ratings. The "Recommended Operating Conditions" table will define the conditions for actual device operation.

Note 5: Unused control inputs must be held HIGH or LOW. They may not float.

#### **DC Electrical Characteristics**

Symbol	Parameter	Conditions	v <sub>cc</sub>	$T_A = -40$ °C to $+85$ °C		Units
Зуппоп		Conditions	(V)	Min	Max	Ollits
V <sub>IH</sub>	HIGH Level Input Voltage		2.3 – 2.7	1.7		V
			2.7 – 3.6	2.0		•
V <sub>IL</sub>	LOW Level Input Voltage		2.3 – 2.7		0.7	V
			2.7 – 3.6		0.8	V
V <sub>OH</sub>	HIGH Level Output Voltage	I <sub>OH</sub> = -100 μA	2.3 – 3.6	V <sub>CC</sub> - 0.2		
		$I_{OH} = -4 \text{ mA}$	2.3	1.8		
		$I_{OH} = -4 \text{ mA}$	2.7	2.2		V
	1	I <sub>OH</sub> = -6 mA	3.0	2.4		v
		$I_{OH} = -8 \text{ mA}$	2.7	2.0		
		I <sub>OH</sub> = -12 mA	3.0	2.0		
V <sub>OL</sub>	LOW Level Output Voltage	I <sub>OL</sub> = 100 μA	2.3 - 3.6		0.2	
		I <sub>OL</sub> = 4 mA	2.3		0.6	
		I <sub>OL</sub> = 4 mA	2.7		0.4	V
		I <sub>OL</sub> = 6 mA	3.0		0.55	•
		I <sub>OL</sub> = 8 mA	2.7		0.6	
		I <sub>OL</sub> = 12 mA	3.0		0.8	
II	Input Leakage Current	$0 \leq V_I \leq 5.5$	2.3 – 3.6		±5.0	μА
l <sub>OZ</sub>	3-STATE Output Leakage	$0 \le V_O \le 5.5V$	2.3 – 3.6		±5.0	μА
		$V_I = V_{IH}$ or $V_{IL}$				hat,

Note 4:  $I_O$  Absolute Maximum Rating must be observed.

## DC Electrical Characteristics (Continued)

Symbol	Parameter	Conditions	V <sub>CC</sub>	T <sub>A</sub> = -40°0	C to +85°C	Units
- Cymbol	T di difficio	Conditions	(V)	Min	Max	0
I <sub>OFF</sub>	Power-Off Leakage Current	V <sub>IN</sub> or V <sub>O</sub> = 5.5V	0		10	μΑ
I <sub>CC</sub>	Quiescent Supply Current	V <sub>I</sub> = V <sub>CC</sub> or GND	2.3 – 3.6		20	μΑ
$\Delta I_{CC}$	Increase in I <sub>CC</sub> per Input	V <sub>IH</sub> = V <sub>CC</sub> -0.6V	2.3 – 3.6		500	μА

Note 6: An external driver must source at least the specified current to switch from LOW-to-HIGH.

Note 7: An external driver must sink at least the specified current to switch from HIGH-to-LOW.

#### **AC Electrical Characteristics**

Symbol			$T_A = -40$ °C to $+85$ °C, $R_L = 500 \Omega$					
		$V_{CC}=3.3V\pm0.3V$		$V_{CC}=2.7V$		$V_{CC}=2.5V\pm0.2V$		Units
	Parameter	C <sub>L</sub> =	C <sub>L</sub> = 50 pF		C <sub>L</sub> = 50 pF		C <sub>L</sub> = 30 pF	
		Min	Max	Min	Max	Min	Max	1
t <sub>PHL</sub>	Propagation Delay	1.0	5.3	1.0	6.0	1.0	6.4	
t <sub>PLH</sub>	Data to Output	1.0	5.3	1.0	6.0	1.0	6.4	ns
t <sub>PZL</sub>	Output Enable Time	1.0	6.3	1.0	7.1	1.0	8.2	
t <sub>PZH</sub>		1.0	6.3	1.0	7.1	1.0	8.2	ns
t <sub>PLZ</sub>	Output Disable Time	1.0	5.4	1.0	5.7	1.0	6.5	
t <sub>PHZ</sub>		1.0	5.4	1.0	5.7	1.0	6.5	ns
toshl	Output to Output Skew (Note 8)		1.0					20
toslh			1.0					ns

Note 8: Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t<sub>OSHL</sub>) or LOW-to-HIGH (t<sub>OSLH</sub>). Parameter guaranteed by design.

## **Dynamic Switching Characteristics**

Symbol	Parameter	Conditions	V <sub>CC</sub>	$T_A = 25^{\circ}C$	Units
			(V)	Typical	
V <sub>OLP</sub>	Quiet Output Dynamic Peak V <sub>OL</sub>	$C_L = 50 \text{ pF}, V_{IH} = 3.3V, V_{IL} = 0V$	3.3	0.35	V
		$C_L = 30 \text{ pF}, V_{IH} = 2.5 \text{V}, V_{IL} = 0 \text{V}$	2.5	0.25	V
V <sub>OLV</sub>	Quiet Output Dynamic Valley V <sub>OL</sub>	$C_L = 50 \text{ pF}, V_{IH} = 3.3 \text{V}, V_{IL} = 0 \text{V}$	3.3	-0.35	V
		$C_L = 30 \text{ pF}, V_{IH} = 2.5 \text{V}, V_{IL} = 0 \text{V}$	2.5	-0.25	V

## Capacitance

Symbol	Parameter	Conditions	Typical	Units
C <sub>IN</sub>	Input Capacitance	$V_{CC} = Open, V_I = 0V \text{ or } V_{CC}$	7	pF
C <sub>OUT</sub>	Output Capacitance	$V_{CC} = 3.3V$ , $V_I = 0V$ or $V_{CC}$	8	pF
C <sub>PD</sub>	Power Dissipation Capacitance	$V_{CC} = 3.3V, V_{I} = 0V \text{ or } V_{CC}, f = 10 \text{ MHz}$	20	pF

#### AC LOADING and WAVEFORMS Generic for LCX Family

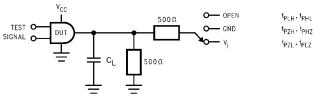
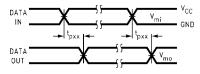
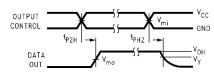


FIGURE 1. AC Test Circuit (C<sub>L</sub> includes probe and jig capacitance)

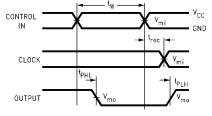
V <sub>I</sub>	CL
6V for V <sub>CC</sub> = 3.3V, 2.7V	50 pF
$V_{CC}$ * 2 for $V_{CC}$ = 2.5V	30 pF



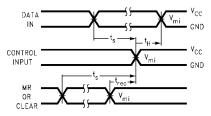
**Waveform for Inverting and Non-Inverting Functions** 



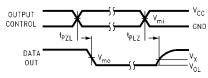
3-STATE Output High Enable and Disable Times for Logic



Propagation Delay. Pulse Width and  $\mathbf{t}_{\text{rec}}$  Waveforms



Setup Time, Hold Time and Recovery Time for Logic



3-STATE Output Low Enable and Disable Times for Logic

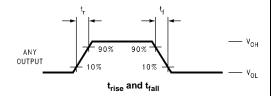
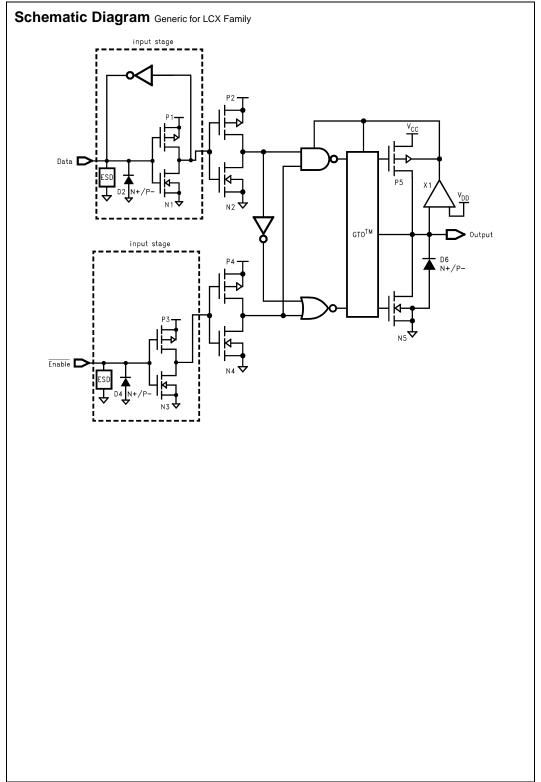
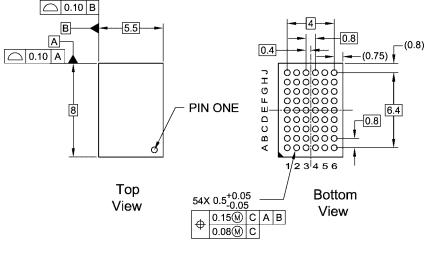


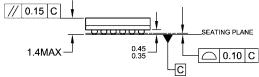
FIGURE 2. Waveforms (Input Characteristics; f = 1MHz,  $t_r = t_f = 3ns$ )

Symbol	V <sub>cc</sub>			
Symbol	3.3V ± 0.3V	2.7V	2.5V ± 0.2V	
$V_{mi}$	1.5V	1.5V	V <sub>CC</sub> /2	
V <sub>mo</sub>	1.5V	1.5V	V <sub>CC</sub> /2	
V <sub>x</sub>	V <sub>OL</sub> + 0.3V	V <sub>OL</sub> + 0.3V	V <sub>OL</sub> + 0.15V	
V <sub>y</sub>	V <sub>OH</sub> – 0.3V	V <sub>OH</sub> – 0.3V	V <sub>OH</sub> – 0.15V	



#### Physical Dimensions inches (millimeters) unless otherwise noted



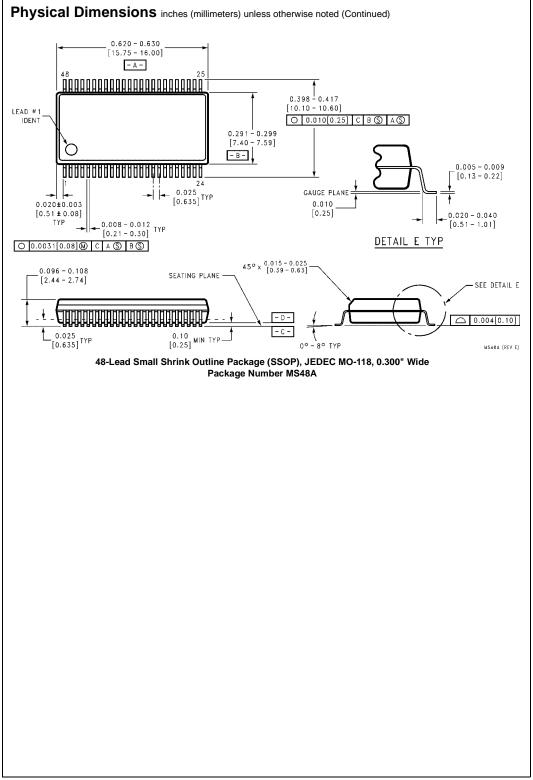


#### NOTES:

- A. THIS PACKAGE CONFORMS TO JEDEC M0-205
- B. ALL DIMENSIONS IN MILLIMETERS
- C. LAND PATTERN RECOMMENDATION: NSMD (Non Solder Mask Defined)
  .35MM DIA PADS WITH A SOLDERMASK OPENING OF .45MM CONCENTRIC TO PADS
  D. DRAWING CONFORMS TO ASME Y14.5M-1994

#### BGA54ArevD

54-Ball Fine-Pitch Ball Grid Array (FBGA), JEDEC MO-205, 5.5mm Wide Package Number BGA54A Preliminary



#### Physical Dimensions inches (millimeters) unless otherwise noted (Continued) 12.50±0.10 0.40 TYP -B-99. 9.20 8.10 50. O.2 C B A ALL LEAD TIPS PIN #1 IDENT 0.50 LAND PATTERN RECOMMENDATION 0.1 C SEE DETAIL A 0.90+0.15 ALL LEAD TIPS 0.09-0.20 0.10±0.05 0.17-0.27 0.50 ♦ 0.13@ A BS CS 12.00' TOP & BOTTOM DIMENSIONS ARE IN MILLIMETERS R0.16 GAGE PLANE 0.25 NOTES: A. CONFORMS TO JEDEC REGISTRATION MO-153, VARIATION ED, DATE 4/97. B. DIMENSIONS ARE IN MILLIMETERS. SEATING PLANE 0.60±0.10 1.00 C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS. D. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1982. DETAIL A MTD48REVC

48-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 6.1mm Wide Package Number MTD48

Fairchild does not assume any responsibility for use of any circuitry described, no circuit patent licenses are implied and Fairchild reserves the right at any time without notice to change said circuitry and specifications.

#### LIFE SUPPORT POLICY

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF THE PRESIDENT OF FAIRCHILD SEMICONDUCTOR CORPORATION. As used herein:

- Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury to the user.
- A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

www.fairchildsemi.com

ON Semiconductor and in are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at <a href="www.onsemi.com/site/pdt/Patent-Marking.pdf">www.onsemi.com/site/pdt/Patent-Marking.pdf</a>. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor and see any inability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and ex

#### **PUBLICATION ORDERING INFORMATION**

#### LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor 19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com N. American Technical Support: 800–282–9855 Toll Free USA/Canada
Europe, Middle East and Africa Technical Support:
Phone: 421 33 790 2910

Phone: 421 33 790 2910

Japan Customer Focus Center

Phone: 81–3–5817–1050

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative

## **X-ON Electronics**

Largest Supplier of Electrical and Electronic Components

Click to view similar products for Buffers & Line Drivers category:

Click to view products by ON Semiconductor manufacturer:

Other Similar products are found below:

LXV200-024SW 74AUP2G34FW3-7 HEF4043BP PI74FCT3244L MC74HCT365ADTR2G Le87401NQC Le87402MQC 028192B
042140C 051117G 070519XB NL17SZ07P5T5G NLU1GT126AMUTCG 74AUP1G17FW5-7 74LVC2G17FW4-7 CD4502BE 59628982101PA 5962-9052201PA 74LVC1G125FW4-7 NL17SH17P5T5G NL17SH125P5T5G NLV37WZ07USG RHRXH162244K1
74AUP1G34FW5-7 74AUP1G07FW5-7 74LVC2G126RA3-7 NLX2G17CMUTCG 74LVCE1G125FZ4-7 Le87501NQC 74AUP1G126FW5-7 TC74HC4050AP(F) 74LVCE1G07FZ4-7 NLX3G16DMUTCG NLX2G06AMUTCG NLVVHC1G50DFT2G NLU2G17AMUTCG
LE87100NQC LE87290YQC LE87290YQCT LE87511NQC LE87511NQCT LE87557NQC LE87557NQCT LE87614MQC
LE87614MQCT 74AUP1G125FW5-7 NLU2G16CMUTCG MC74LCX244MN2TWG NLV74VHC125DTR2G NL17SG126DFT2G